

STRESS EVOLUTION AND NANOMORPHOLOGY DURING THIN FILM DEPOSITION - IN SITU NANOMECHANICS

Jerry Floro

Sandia National Laboratories, Surface and Interface Sciences
505-844-4708
jfloro@sandia.gov

Group IV Molecular Beam Epitaxy + In Situ Diagnostics

Light Scattering Spectroscopy (LSSp):
surface spatial period and correlation length

Additional experimental capabilities:

- Atomic hydrogen source
- Kaufman ion source for high rate etching, sputter deposition, and energetic deposition
- Negative ion deposition source for Si and C
- Atomic force microscopy
- Gas ambient annealing

Reflection High Energy Electron Diffraction (RHEED):
surface crystallography and nanoroughness

Multi-beam Optical Stress Sensor (MOSS):
substrate curvature measurement for sensitive real-time stress evolution

Current Research I: Surface Nanosculpting Using Strain Layer Self Assembly

QUASI-EQUILIBRIUM REGIME
Repetition-driven morphological evolution in high density arrays

THICKNESS
Quantum ridges
Quantum wires
Discrete quantum molecules
Dense quantum molecules

HIGH SUPERSATURATION REGIME
Complex structures by cooperative nucleation

Self-assembly of complex structures, including quantum dots (storage), quantum molecules (logic) and quantum wires (interconnects).

Stress-Thickness (GPa·Å)
Spatial Period (Å)
Thickness (Å)
Temperature
Growth Time
Anneal Time
Degree of Order
LATERAL ORDER
DOT DENSITY
CRITICAL TRANSITION VOLUME
Areal Coverage

RESEARCH INTERESTS
Strain-layer heteroepitaxy
Self assembly of quantum nanostructures
Strain relaxation mechanisms
SiGeC alloys
Effects of hydrogen on growth kinetics
Energetic deposition
Amorphous SiGe

Sean J. Hearne
Sandia National Laboratories, Nanostructure and Semiconductor Physics
505-844-0804
sjhearn@sandia.gov

Electrodeposition + In Situ Diagnostics

System Capabilities:

- MOSS measurements during electrodeposition
- Three and four point probe electrochemical measurements

Electrodeposition allows for unique studies of the effect of restricted geometries (via selective area growth) on stress and microstructure

Island Coalescence

Hertzian contact model for island coalescence predicts a strong dependence of stress on island geometry.

Unpatterned films
Build upon studies of discrete phenomena to understand stress evolution in blanket films.

Decreased plating rate results in decreased stress

TEM studies of Nano-mechanical deformation processes

Quantitative stress-strain measurements in-situ of a TEM

MEMS-based tensile tester designed for actuation in-situ in a TEM.
Gauge section located over Becht hole through the water to facilitate plan-view TEM imaging during actuation.

Collaborator: M. De Boer

Analysis technique

Ex-situ interferometry is used to characterize the stress-strain response of the MEMS structures.

Loaded
Unloaded

Stress-strain response determined from finite element analysis of data

Developing capability to build device using both lift-off masks and electroplating to allow study of nano-structured Al, Ni, and Cu.

TEM micrographs of unloading Al beam in actual structure